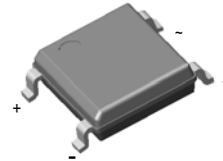




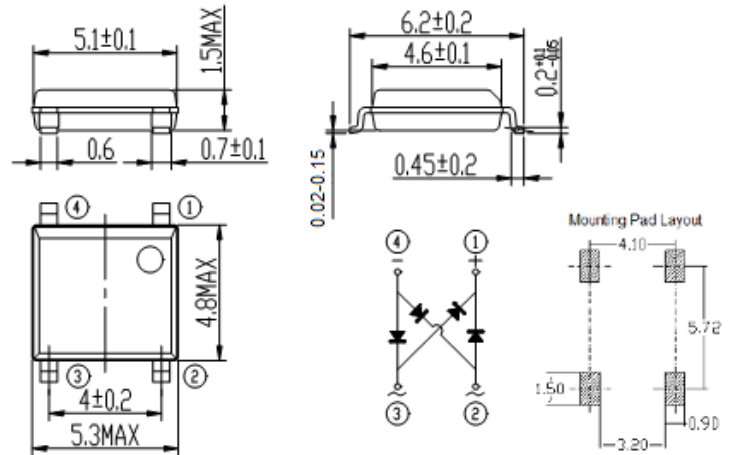
Features

- Low Profile: Typical height of 1.4mm
- Ideal for automated placement
- High surge current capability
- Solder Dip 260 , 10seconds



Mechanical Data

- Case:SOPA-4
- Epoxy meets UL-94V-0 Flammability rating
- Terminals:Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity:As markde on body



Maximum Ratings & Electrical Characteristics Ratings at 25

ambient temperature unless otherwise specified.

Parameter	Symbol	LB2SA	LB4SA	LB6SA	LB8SA	LB10SA	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average forward output rectified current	$I_{F(AV)}$					0.8	A
on glass-epoxy P.C.B						1.0	
on aluminum substrate							
Peak forward surge current 8.3 ms single sine-wave	I_{FSM}					25	A
superimposed on rated load (JEDEC Method)							
Rating for fusig (t<8.3ms)	I^2t					2.6	A ² sec
Maximum instantaneous forward voltage drop	V_F					0.95	V
per diode at 0.4A							
Maximum DC reverse current at TA=25	I_R					5	μA
rated DC blocking voltage per leg TA=125						500	
Typical thermal resistance per leg (Note 1)	$R_{θJA}$					80	/W
	$R_{θJL}$					25	
Operating junction temperature range	T_J					-55 to +150	
Storage temperature range	T_{STG}					-55 to +150	

- Notes:** 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.
2. JEDEC registered values



RATINGS AND CHARACTERISTIC CURVES

(TA=25 unless otherwise noted)

